

74LVCU04A-Q100

Hex unbuffered inverter

Rev. 1 — 21 September 2016

Product data sheet

1. General description

The 74LVCU04A-Q100 is a general purpose hex unbuffered inverter. Each of the six inverters is a single stage with unbuffered outputs.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$
- Wide supply voltage range from 1.2 V to 3.6 V
- Inputs accept voltages up to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Complies with JEDEC standard:
 - ◆ JESD8-7A (1.65 V to 1.95 V)
 - ◆ JESD8-5A (2.3 V to 2.7 V)
 - ◆ JESD8-C/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0 Ω)



3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74LVCU04AD-Q100	-40 °C to +125 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74LVCU04APW-Q100	-40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1

4. Functional diagram

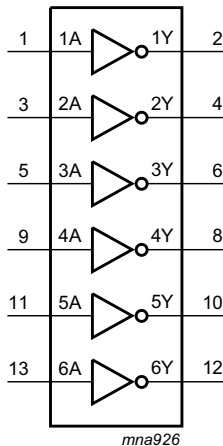


Fig 1. Logic symbol

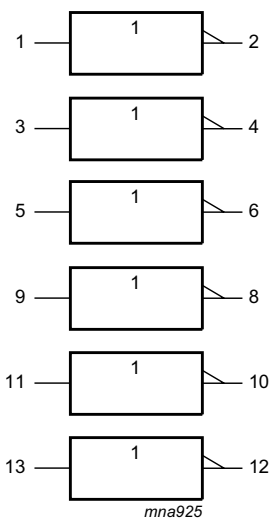


Fig 2. IEC logic symbol

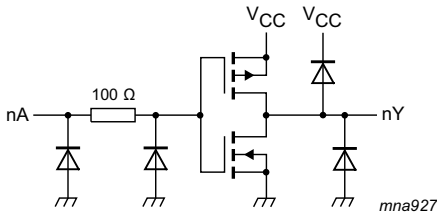


Fig 3. Schematic diagram for one inverter

5. Pinning information

5.1 Pinning

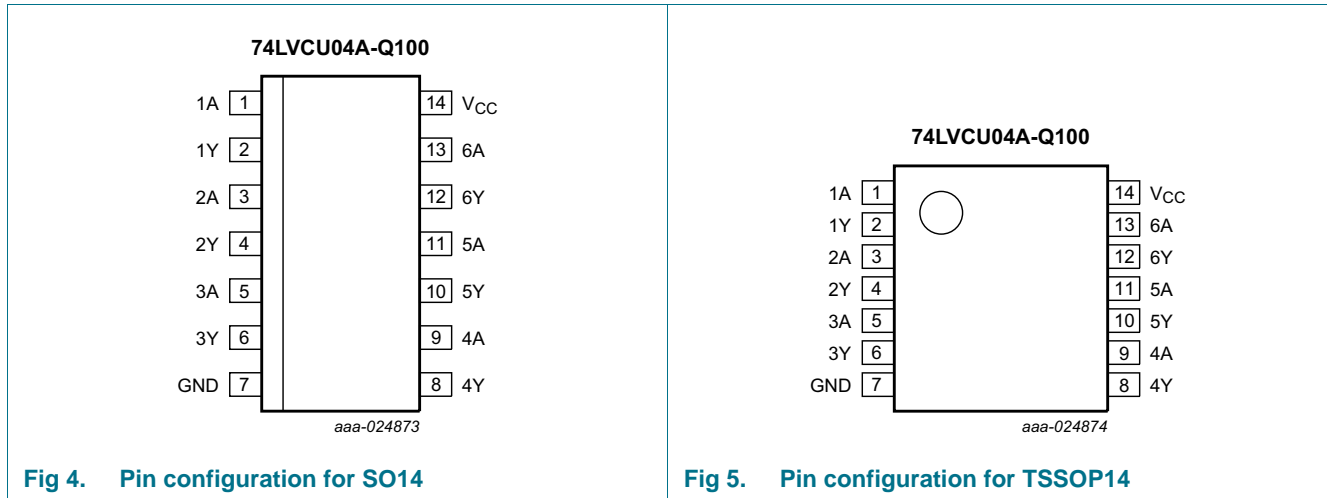


Fig 4. Pin configuration for SO14

Fig 5. Pin configuration for TSSOP14

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 2A, 3A, 4A, 5A, 6A	1, 3, 5, 9, 11, 13	data input
1Y, 2Y, 3Y, 4Y, 5Y, 6Y	2, 4, 6, 8, 10, 12	data output
GND	7	ground (0 V)
V _{CC}	14	supply voltage

6. Functional description

Table 3. Function table^[1]

Input nA	Output nY
L	H
H	L

[1] H = HIGH voltage level; L = LOW voltage level

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+6.5	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
V_I	input voltage		[1] -0.5	+6.5	V
I_{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	± 50	mA
V_O	output voltage		[2] -0.5	$V_{CC} + 0.5$	V
I_O	output current	$V_O = 0$ V to V_{CC}	-	± 50	mA
I_{CC}	supply current		-	100	mA
I_{GND}	ground current		-100	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[3] -	500	mW

[1] The minimum input voltage ratings may be exceeded if the input current ratings are observed.

[2] The output voltage ratings may be exceeded if the output current ratings are observed.

[3] For SO14 packages: above 70 °C the value of P_{tot} derates linearly with 8 mW/K.
For TSSOP14 packages: above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		1.65	-	3.6	V
		functional	1.2	-	-	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature	in free air	-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65$ V to 2.7 V	0	-	20	ns/V
		$V_{CC} = 2.7$ V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{IH}	HIGH-level input voltage	V _{OL(max)} = 0.5 V; I _O = -100 μA						
		V _{CC} = 1.2 V	1.08	-	-	1.12	-	V
		V _{CC} = 1.65 V to 1.95 V	1.3	-	-	1.5	-	V
		V _{CC} = 2.3 V to 2.7 V	1.8	-	-	2.0	-	V
		V _{CC} = 3.0 V	2.0	-	-	2.4	-	V
		V _{CC} = 3.6 V	2.4	-	-	2.8	-	V
V _{IL}	LOW-level input voltage	V _{OH(min)} = V _{CC} - 0.5 V; I _O = -100 μA						
		V _{CC} = 1.2 V	-	-	0.12	-	0.1	V
		V _{CC} = 1.65 V to 1.95 V	-	-	0.6	-	0.4	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.6	-	0.5	V
		V _{CC} = 3.0 V	-	-	1.0	-	0.6	V
		V _{CC} = 3.6 V	-	-	1.2	-	0.7	V
V _{OH}	HIGH-level output voltage	V _I = GND						
		V _{CC} = 3.0 V; I _O = -100 μA	V _{CC} - 0.2	-	-	V _{CC} - 0.3	-	V
		V _{CC} = 1.65 V; I _O = -4 mA	1.2	-	-	1.05	-	V
		V _{CC} = 2.3 V; I _O = -8 mA	1.8	-	-	1.65	-	V
		V _{CC} = 2.7 V; I _O = -12 mA	2.2	-	-	2.05	-	V
		V _{CC} = 3.0 V; I _O = -18 mA	2.4	-	-	2.25	-	V
		V _{CC} = 3.0 V; I _O = -24 mA	2.2	-	-	2.0	-	V
V _{OL}	LOW-level output voltage	V _I = V _{CC}						
		V _{CC} = 3.0 V; I _O = 100 μA	-	-	0.20	-	0.60	V
		V _{CC} = 1.65 V; I _O = 4 mA	-	-	0.45	-	0.65	V
		V _{CC} = 2.3 V; I _O = 8 mA	-	-	0.60	-	0.80	V
		V _{CC} = 2.7 V; I _O = 12 mA	-	-	0.40	-	0.30	V
		V _{CC} = 3.0 V; I _O = 24 mA	-	-	0.55	-	0.80	V
I _I	input leakage current	V _{CC} = 3.6 V; V _I = 5.5 V or GND	-	±0.1	±5	-	±20	μA
I _{CC}	supply current	V _{CC} = 3.6 V; V _I = V _{CC} or GND; I _O = 0 A	-	0.1	10	-	40	μA
ΔI _{CC}	additional supply current	per input pin; V _{CC} = 2.7 V to 3.6 V; V _I = V _{CC} - 0.6 V; I _O = 0 A	-	5	500	-	5000	μA
C _I	input capacitance	V _{CC} = 0 V to 3.6 V; V _I = GND to V _{CC}	-	5.5	-	-	-	pF

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
t _{pd}	propagation delay	nA to nY; see Figure 6 ^[2]						
		V _{CC} = 1.2 V	-	6.0	-	-	-	ns
		V _{CC} = 1.65 V to 1.95 V	0.3	3.7	7.8	0.3	9.0	ns
		V _{CC} = 2.3 V to 2.7 V	0.5	2.2	4.4	0.5	5.2	ns
		V _{CC} = 2.7 V	0.5	2.0	4.5	0.5	6.0	ns
		V _{CC} = 3.0 V to 3.6 V	0.5	2.0	4.0	0.5	5.0	ns
t _{sk(o)}	output skew time	V _{CC} = 3.0 V to 3.6 V ^[3]	-	-	1.0	-	1.5	ns
C _{PD}	power dissipation capacitance	per inverter; V _I = GND to V _{CC} ^[4]						
		V _{CC} = 1.65 V to 1.95 V	-	2.3	-	-	-	pF
		V _{CC} = 2.3 V to 2.7 V	-	5.5	-	-	-	pF
		V _{CC} = 3.0 V to 3.6 V	-	8.4	-	-	-	pF

[1] Typical values are measured at T_{amb} = 25 °C and V_{CC} = 1.2 V, 1.8 V, 2.5 V, 2.7 V, and 3.3 V respectively.

[2] t_{pd} is the same as t_{PLH} and t_{PHL}.

[3] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz; f_o = output frequency in MHz

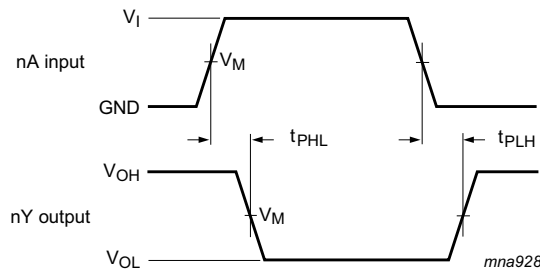
C_L = output load capacitance in pF

V_{CC} = supply voltage in Volts

N = number of inputs switching

Σ(C_L × V_{CC}² × f_o) = sum of the outputs

11. Waveforms

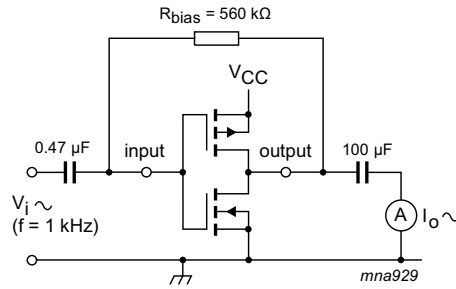


V_M = 1.5 V at V_{CC} ≥ 2.7 V;

V_M = 0.5 × V_{CC} at V_{CC} < 2.7 V;

V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

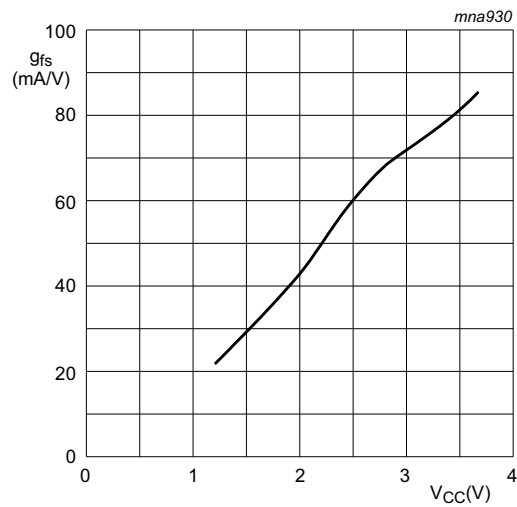
Fig 6. Input (nA) to output (nY) propagation delays



$$g_{fs} = \frac{dI_O}{dV_I}; \text{ at constant } V_O$$

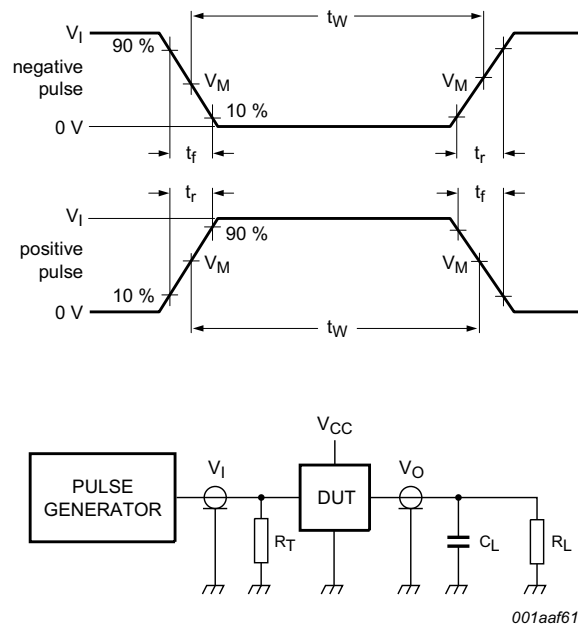
$f_i = 1 \text{ kHz}$ at V_O is constant

Fig 7. Test setup for measuring forward transconductance



T_{amb} = 25 °C

Fig 8. Typical forward transconductance as a function of supply voltage



001aaf615

Test data is given in [Table 8](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

Fig 9. Test circuit for measuring switching times

Table 8. Test data

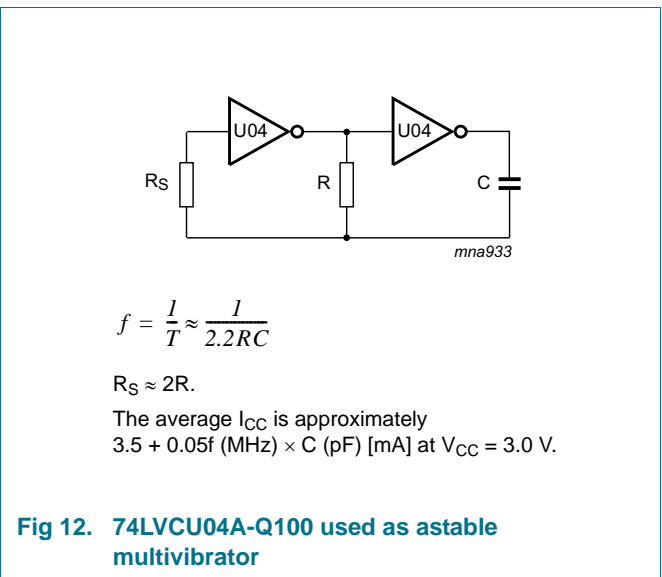
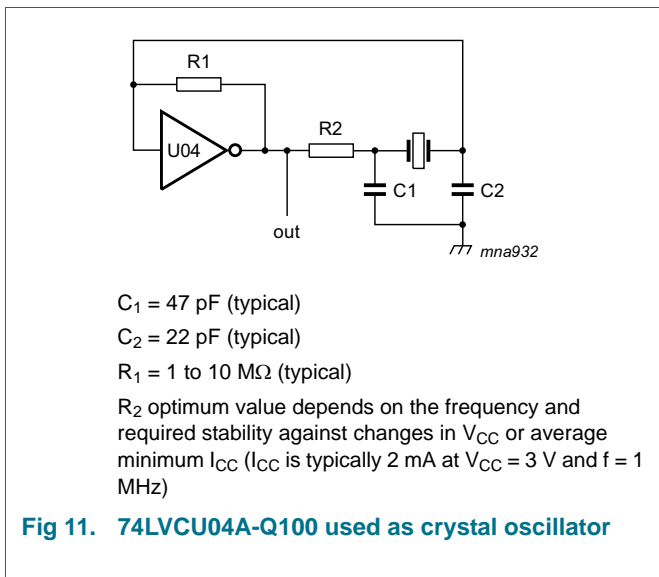
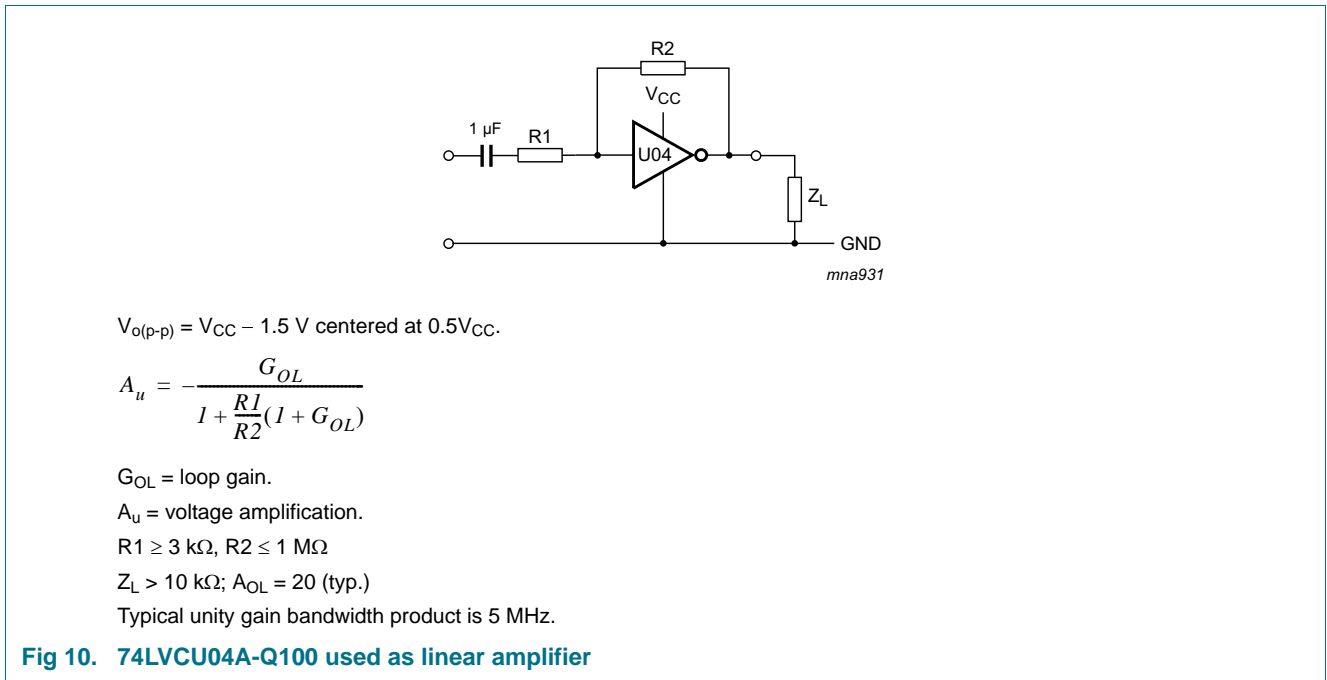
Supply voltage	Input		Load	
	V_I	t_r, t_f	C_L	R_L
1.2 V	V_{CC}	≤ 2 ns	30 pF	1 k Ω
1.65 V to 1.95 V	V_{CC}	≤ 2 ns	30 pF	1 k Ω
2.3 V to 2.7 V	V_{CC}	≤ 2 ns	30 pF	500 Ω
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω

12. Application information

12.1 Application diagrams

Some applications for the 74LVCU04A-Q100 are:

- Linear amplifier: see [Figure 10](#)
- Crystal oscillator designs; see [Figure 11](#)
- Astable multivibrator; see [Figure 12](#)



13. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

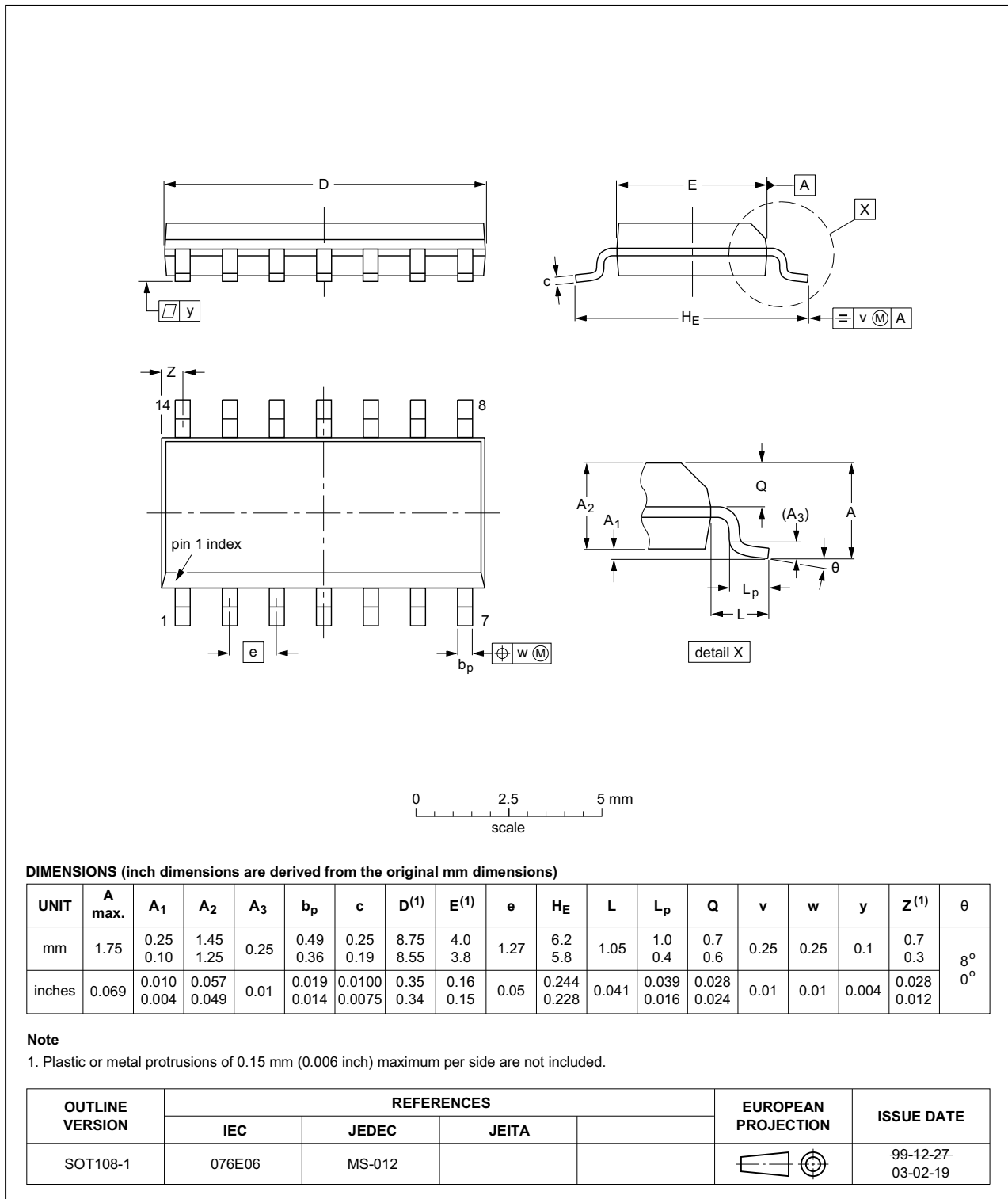


Fig 13. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

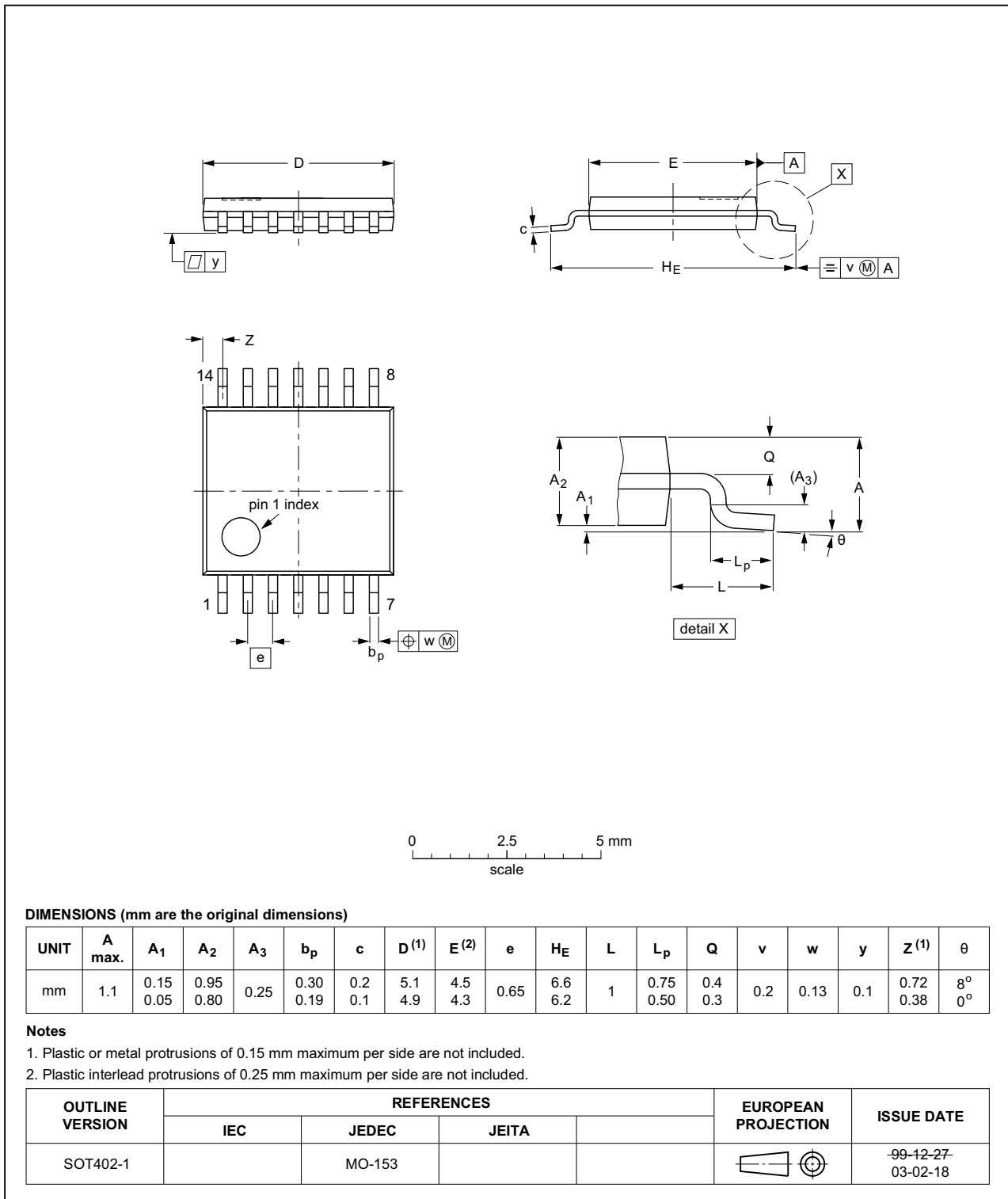


Fig 14. Package outline SOT402-1 (TSSOP14)

14. Abbreviations

Table 9. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic
MIL	Military

15. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVCU04A_Q100 v.1	20160921	Product data sheet	-	-

16. Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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